

Welcome to E-XFL.COM

Understanding <u>Embedded - CPLDs (Complex</u> <u>Programmable Logic Devices)</u>

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixedfunction ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	EE PLD
Delay Time tpd(1) Max	15 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	-
Number of Macrocells	10
Number of Gates	-
Number of I/O	-
Operating Temperature	0°C ~ 75°C (TA)
Mounting Type	Through Hole
Package / Case	24-DIP (0.300", 7.62mm)
Supplier Device Package	24-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/gal20ra10b-15lp

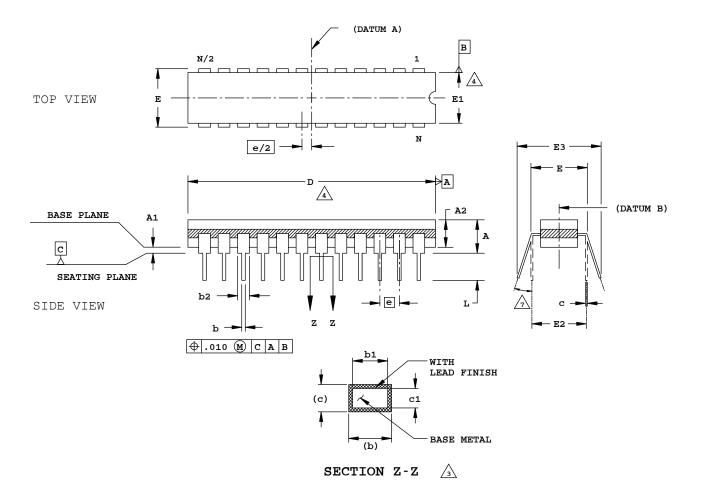
Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



24-Pin (300-Mil) CERDIP

Dimensions in Inches



NOTES:

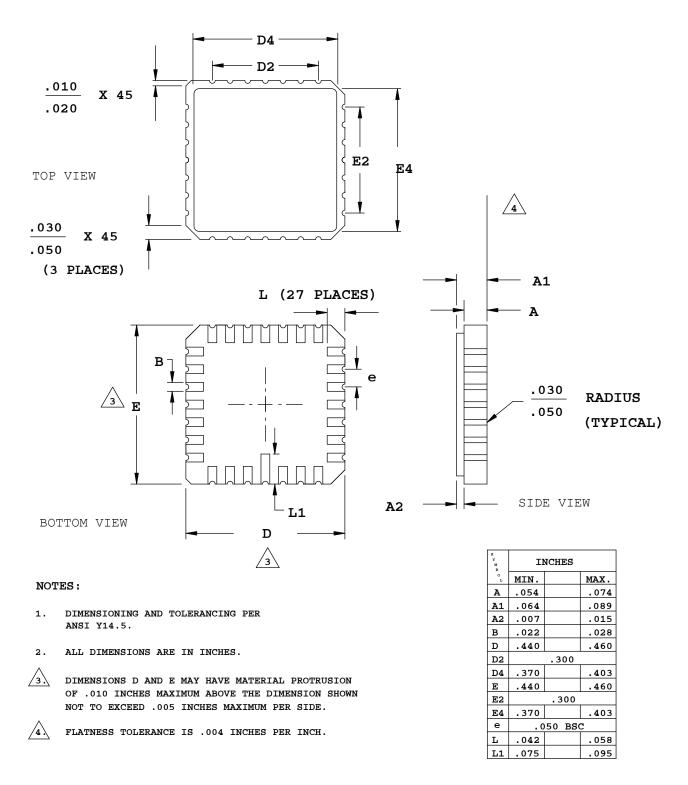
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN INCHES.
- 3. MEASUREMENTS TO BE TAKEN AT A MINIMUM OF .060 INCHES FROM THE LEAD TIP.
- dimensions d and e1 include allowance for glass overrun and meniscus, and lid to base mismatch.
- DIMENSIONS A, A1 AND L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS-003.
- 6. E3 IS TO BE MEASURED AT THE LEAD TIPS.
- /7. ALLOWED LEAD TIP POSITION RANGE.

s Y M B	INCHES		
0 L	MIN.	NOM.	MAX.
A	-	-	.200
A1	.015	-	-
A2	.140	-	.175
b	.015	-	.023
b1	.015	.018	.021
b2	.045	-	.065
с	.008	-	.014
c1	.008	.010	.012
D	1.242	1.250	1.270
Е	.308	-	.325
E1	.280	.288	.296
E2	.300 REF		
E3	.325	-	.410
е	.100 BSC		
L	.125	-	.200
N	24		



28-Pin LCC Package

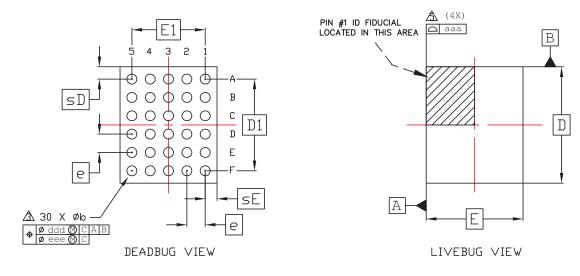
Dimensions in Inches

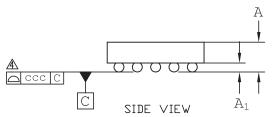




30-Ball WLSC Package

Dimensions in Millimeters





Notes:

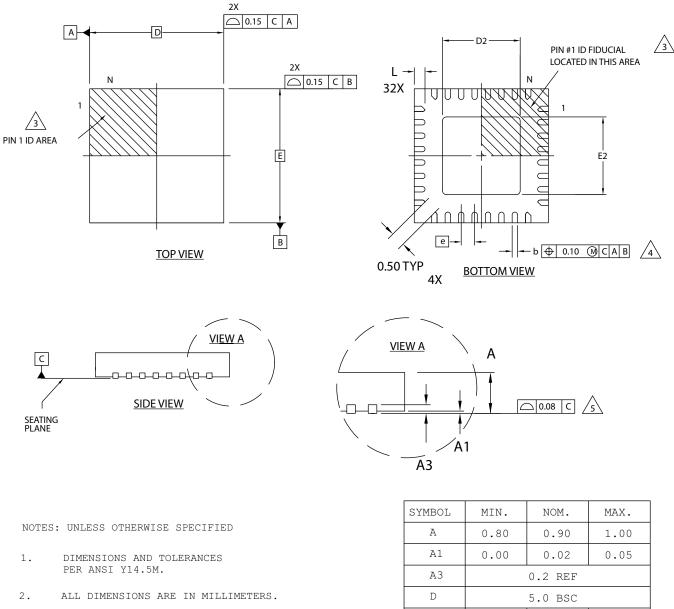
- 1 ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M 1994. 2 ALL DIMENSIONS ARE IN MILLIMETERS.
- A DIMENSION "b" IS MEASURED AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
- ▲ PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CRUWNS OF THE SOLDER BUMPS.
 ▲ BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE
- PACKAGE BODY.

REF.	Min.	Nom.	Max.
Α	-	-	0.600
A1	0.140	-	-
b	0.230	0.260	0.290
D	2.5	537 BSC)
E	2	.114 BSC	;
D1	í	2.00 BSC)
E1		1.60 BSC)
e		0.40 BSC	2
sD	-	0.26	-
sE	-	0.27	-
۵۵۵		0.030	
ССС		0.050	
ddd		0.015	
eee		0.050	



32-Pin QFN Package Option 1: Power Manager II, iCE40[™]

Dimensions in Millimeters



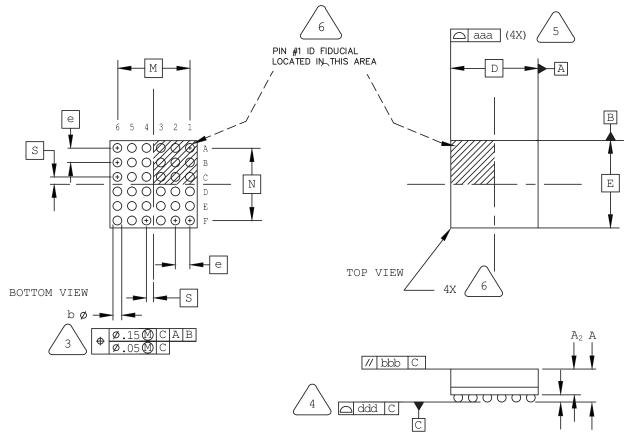
- EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
- DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.
- /5 APPLIES TO EXPOSED PORTION OF TERMINALS.

А	0.80	0.90	1.00
A1	0.00	0.02	0.05
A3	0.2 REF		
D	5.0 BSC		
D2	1.25	2.70	3.75
E	5.0 BSC		
E2	1.25	2.70	3.75
b	0.18	0.24	0.30
е	0.50 BSC		
L	0.30	0.40	0.50



36-Ball ucfBGA Package: iCE40 Ultra™

Dimensions in Millimeters



SIDE	VIEW

NOTES:	UNLESS OTHERWISE SPECIFIED
1.	DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2.	ALL DIMENSIONS ARE IN MILLIMETERS.
3	DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
4	PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5	BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
\cap	

6

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

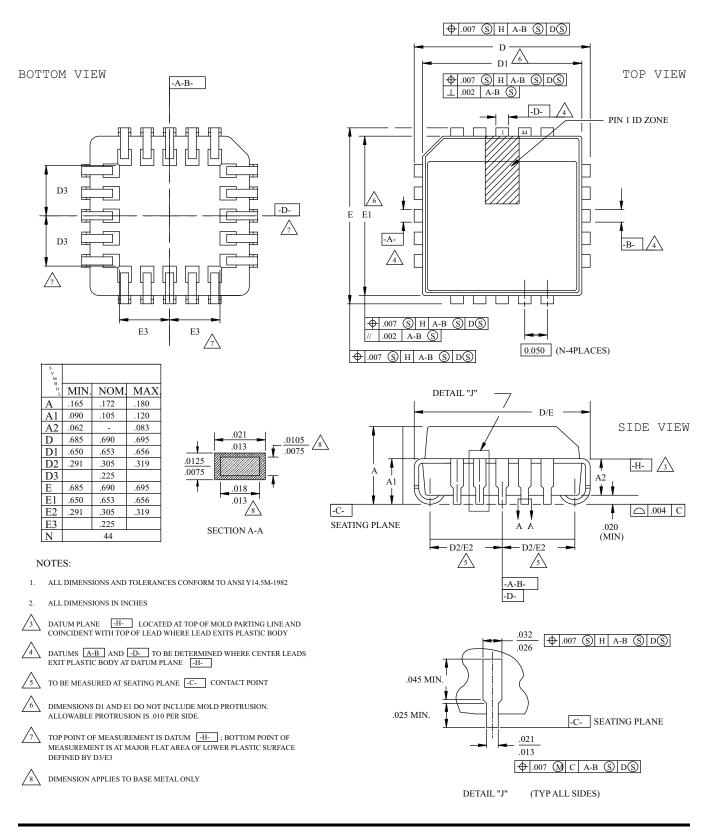
SYMBOL	MIN.	NOM.	MAX.
A	-	0.81	0.91
Al	0.12	_	-
A2	_	_	0.70
D/E	2	.50 BSC	
M/N	2.00 BSC		
S	0.20 BSC		
b	0.20	0.25	0.30
е	0.40 BSC		
aaa	-	-	0.10
bbb	-	_	0.10
ddd	_	_	0.10

 A_1



44-Pin PLCC Package

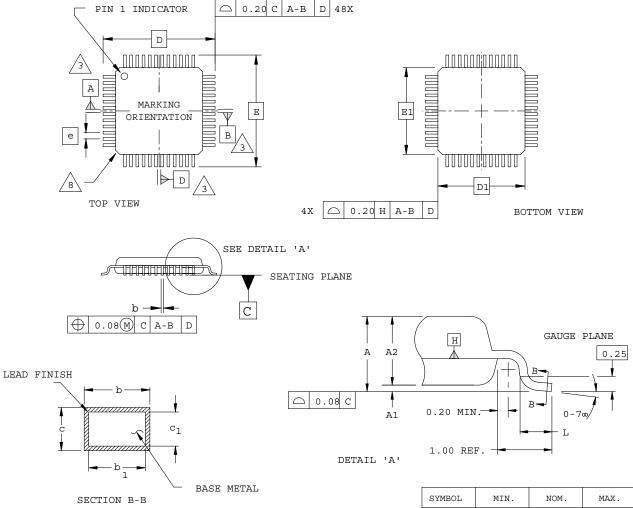
Dimensions in Inches





48-Pin TQFP Package (1.0 mm thick)

Dimensions in Millimeters



NOTES:

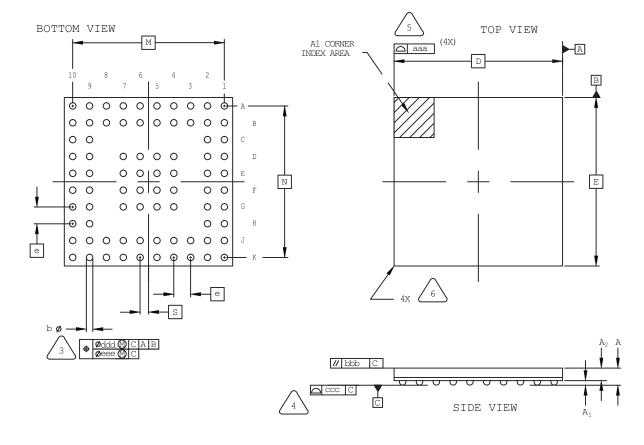
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- $/_3$ datums a, b and d to be determined at datum plane H.
- 4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6. SECTION B-B: THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- 8 EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.20
A1	0.05	-	0.15
A2	.95	1.00	1.05
D		9.00 BSC	
D1		7.00 BSC	
Е	9.00 BSC		
E1	7.00 BSC		
L	0.45	0.60	0.75
N	48		
е	0.50 BSC		
b	0.17 0.22 0.27		
b1	0.17	0.20	0.23
с	0.09	0.15	0.20
c1	0.09	0.13	0.16



80-Ball ctfBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- $\sqrt{3}$

DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].



6

PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

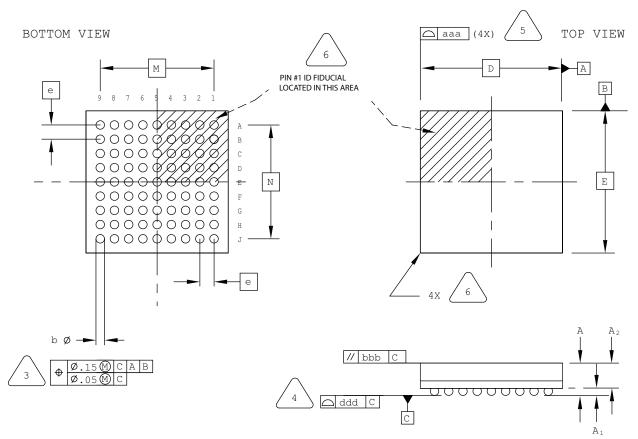
BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
Al	0.11	-	-
A2	0.61	-	-
D/E		6.50 BSC	
M/N		5.85 BSC	
S	0.325 BSC		
b	0.20	0.25	0.30
е	0.65 BSC		
aaa	0.10		
bbb	0.10		
ccc	0.08		
ddd	0.15		
eee	0.05		



81-Ball ucBGA Package

Dimensions in Millimeters



SIDE VIEW

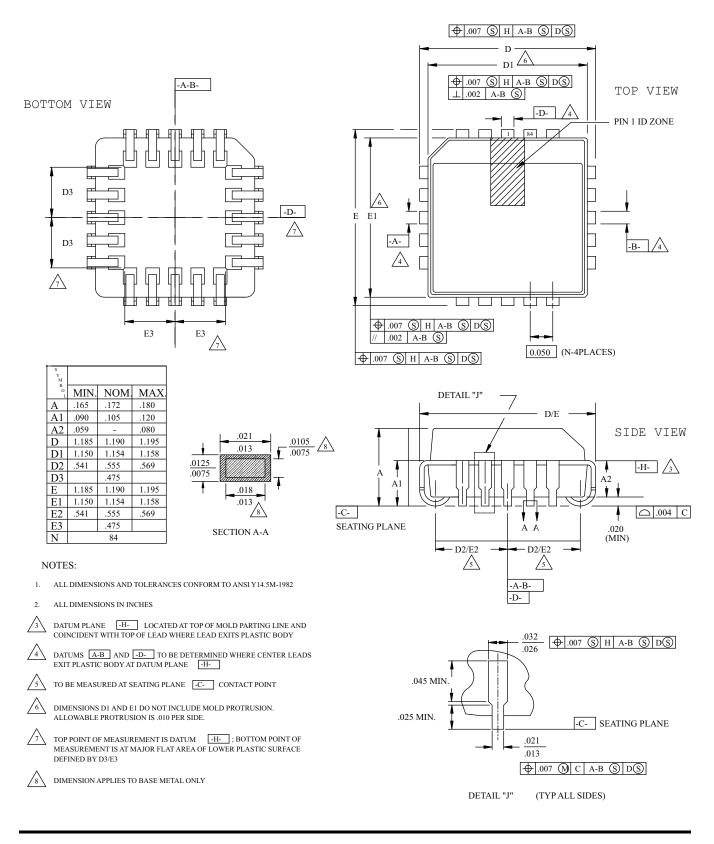
NOTES:	UNLESS OTHERWISE SPECIFIED
1.	DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2.	ALL DIMENSIONS ARE IN MILLIMETERS.
3	DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
4	PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5	BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
6	EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	_	1.00
A1	0.10	-	-
A2	-	-	0.90
D/E	4.00 BSC		
M/N	3.20 BSC		
b	0.20	0.25	0.30
e	0.40 BSC		
aaa	-	-	0.10
bbb	-	-	0.10
ddd	-	-	0.10



84-Pin PLCC Package

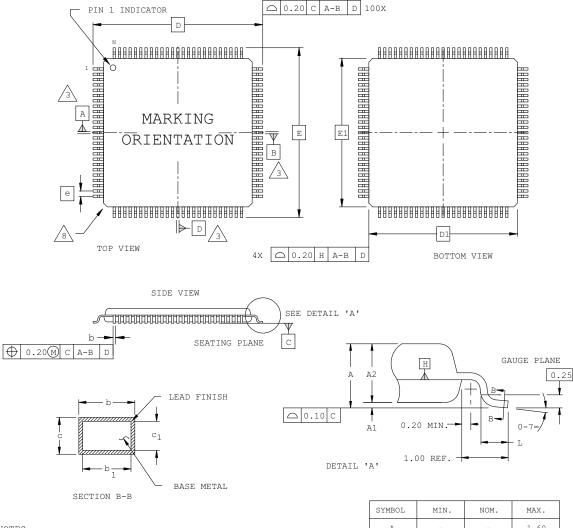
Dimensions in Inches





100-Pin TQFP Package Option 1: MachXO2, MachXO[™], ispMACH[®] 4000

Dimensions in Millimeters



NOTES:

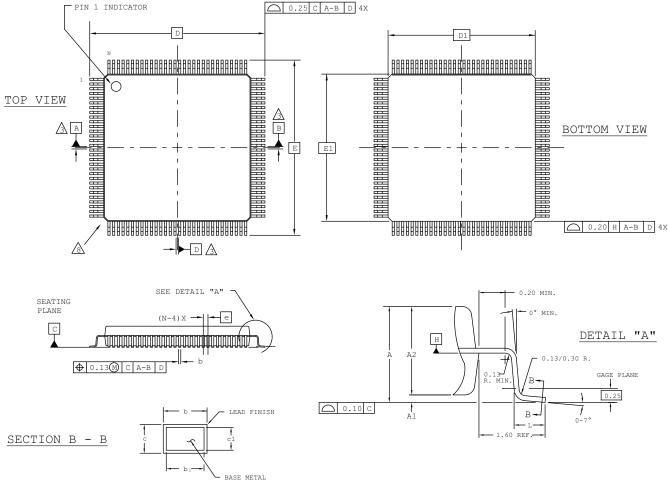
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- $/_3$ datums a, b and d to be determined at datum plane H.
- DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6. SECTION B-B: THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7. Al is defined as the distance from the seating plane to the lowest point on the package body.
- /8 EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.60
A1	0.05	-	0.15
A2	1.35	1.40	1.45
D		16.00 BSC	
D1		14.00 BSC	
E	16.00 BSC		
E1	14.00 BSC		
L	0.45	0.60	0.75
N	100		
e	0.50 BSC		
b	0.17	0.22	0.27
b1	0.17	0.20	0.23
с	0.09	0.15	0.20
c1	0.09	0.13	0.16



160-Pin PQFP Package

Dimensions in Millimeters



NOTES:

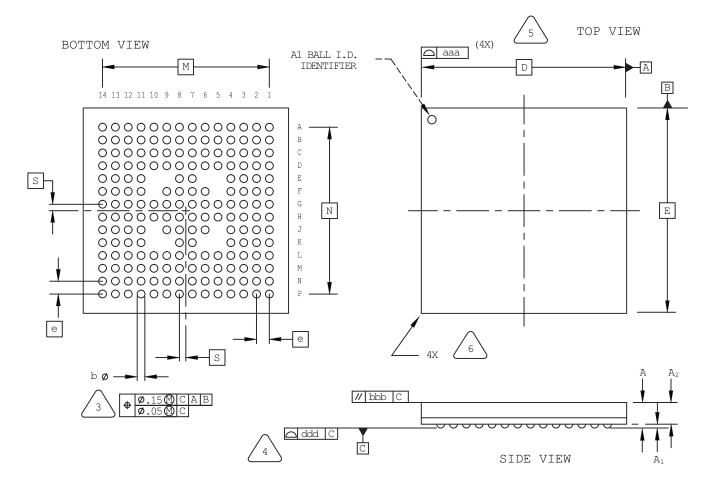
- 1.0 DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2.0 ALL DIMENSIONS ARE IN MILLIMETERS.
- \bigtriangleup datums a, b and d to be determined at datum plane H.
- 4.0 DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 5.0 THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6.0 SECTION B-B: THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7.0 A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- A EXACT SHAPE OF EACH CORNER IS OPTIONAL.
- A EXACT SHAPE OF EXPOSED HEATSINK IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	4.10
A1	0.25	-	0.50
A2	3.20	3.40	3.60
D		31.20 BSC	
D1		28.00 BSC	
E	31.20 BSC		
E1	28.00 BSC		
L	0.73	0.88	1.03
Ν	160		
е	0.65 BSC		
b	0.22 - 0.40		0.40
b1	0.22	0.30	0.36
С	0.11	-	0.23
c1	0.11	0.15	0.19



184-Ball csBGA Package

Dimensions in Millimeters



NOTES:	UNLESS OTHERWISE SPECIFIED
1.	DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2.	ALL DIMENSIONS ARE IN MILLIMETERS.
3	DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
4	PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5	BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

6

SYMBOL	MIN.	NOM.	MAX.
A	1.20	1.35	1.50
A1	0.16	-	_
A2	-	-	1.34
D/E	8	.00 BSC	
M/N	6.50 BSC		
S	0.25 BSC		
b	0.25	0.30	0.35
e	0.50 BSC		
aaa	-	-	0.10
bbb	_	_	0.10
ddd	-	-	0.08



256-Ball ftBGA Package Option 1: ispMACH 4000, MachXO, LatticeXP2

Dimensions in Millimeters

	A1 BALL I.D IDENTIFIEN 16 14 12 10 8 6 4 2 15 13 11 9 7 5 3 1	
s	A B C C C C C C C C C C C C C C C C C C C D C C C C C D C C	
e	0 0	
	$b \not {a} \rightarrow f = s$ $b \not {a} \rightarrow f = s$ $f = f = s$	$ \begin{array}{c c} & & & \\ & & & \\ \hline \\ \hline \\ \hline \\ \hline \\ \hline \\ \\ \hline \\ \\ \\ \\$

NOTES: UNLESS OTHERWISE SPECIFIED

 DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

3

6

- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
 - DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C]

PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

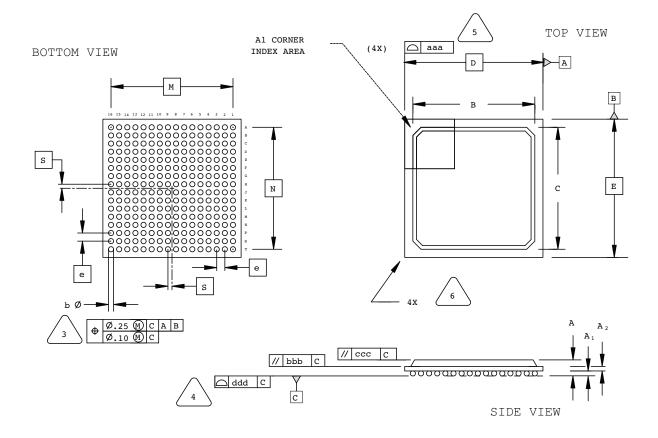
BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

SYMBOL	MIN.	NOM.	MAX.
A	1.25	1.40	1.55
Al	0.30	-	-
A2	-	-	1.25
D/E	1'	7.0 BSC	
M/N	15.0 BSC		
S	0.50 BSC		
b	0.40	0.50	0.60
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.12



256-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

3

DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\fbox{\cite{C}}$



5

6

PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

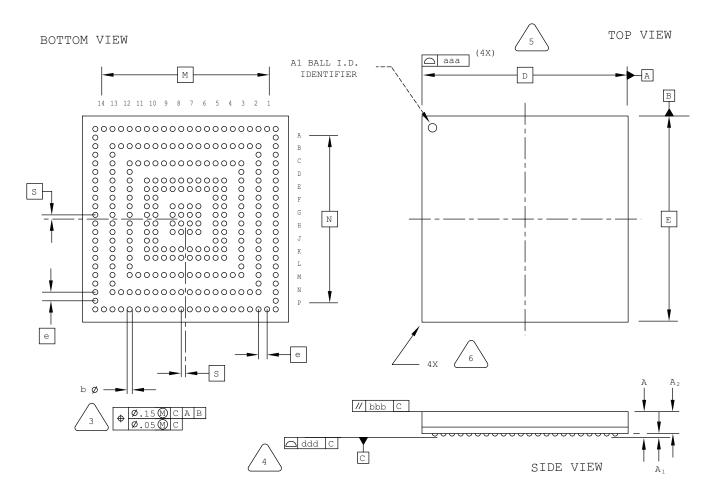
BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

SYMBOL	MIN.	NOM.	MAX.
A	1.30	1.70	2.10
A1	0.30	0.50	0.70
A2	0.30	0.50	0.70
B/C	14.80	15.30	15.80
D/E	17.00 BSC		
M/N	15.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-		
bbb	-	_	0.25
ccc	-	-	0.35
ddd	-	-	0.20



284-Ball csBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED DIMENSIONS AND TOLERANCES 1. PER ANSI Y14.5M. 2. ALL DIMENSIONS ARE IN MILLIMETERS. DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER 3 PARALLEL TO PRIMARY DATUM C PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL 4 CROWNS OF THE SOLDER BALLS. BILATERAL TOLERANCE ZONE IS APPLIED 5 TO EACH SIDE OF THE PACKAGE BODY.

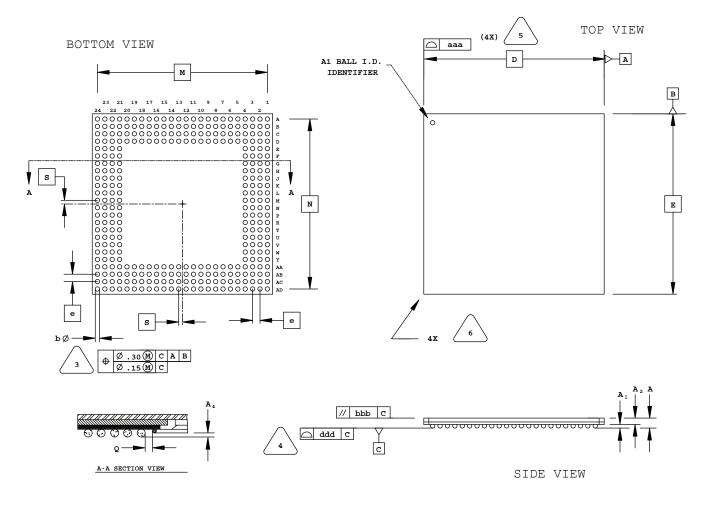
6

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.15	-	_
A2	_	_	0.85
D/E	12	2.00 BSC	
M/N	10.50 BSC		
S	0.25 BSC		
b	0.25	0.31	0.37
е	0.50 BSC		
aaa			0.10
bbb	_	_	0.10
ddd	_	_	0.08



320-Ball SBGA Package

Dimensions in Millimeters



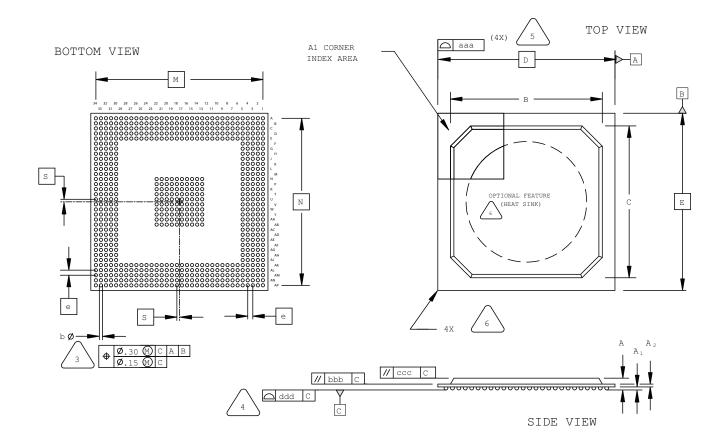
NOTES:	UNLESS OTHERWISE SPECIFIED
1.	DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2.	ALL DIMENSIONS ARE IN MILLIMETERS.
3	DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
4	PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5	BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
6	EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	1.70
A1	0.50	0.65	0.80
A2	0.80	0.90	1.00
D/E	3:	1.00 BSC	
M/N	29	9.21 BSC	
s	0.635 BSC		
b	0.60	0.75	0.90
e	1.27 BSC		
Q	0.25	-	-
A4	0.10	-	-
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.20



680-Ball fpBGA Package

(with or without Internal Heat Spreader) Dimensions in Millimeters



NOTES:	UNLESS OTHERWISE SPECIFIED
1.	DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
2.	ALL DIMENSIONS ARE IN MILLIMETERS.
3	DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
4	PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5	BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

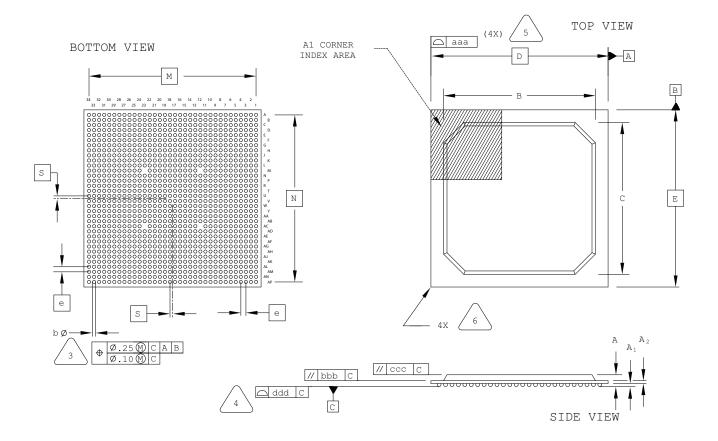
6

SYMBOL	MIN.	NOM.	MAX.
A	1.90	2.25	2.60
A1	0.30	0.50	0.70
A2	0.40	0.60	0.80
B/C	29.80	30.30	30.80
D/E	35	5.00 BSC	
M/N	33.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20



1152-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

 DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

3

4

5

6

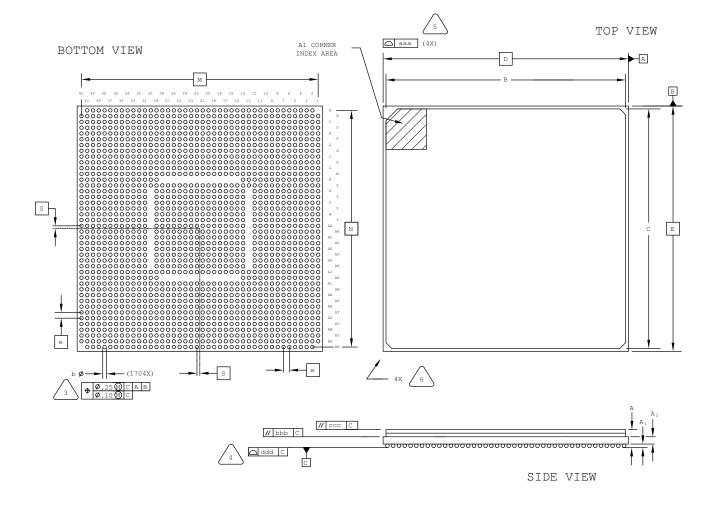
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
 - DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C
 - PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 - BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
 - EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
 - Note: Depopulated ball locations are M12, M23, AC12, and AC23.

SYMBOL	MIN.	NOM.	MAX.
A	1.90	2.25	2.60
A1	0.30	0.50	0.70
A2	0.40	0.60	0.80
B/C	29.80	30.30	30.80
D/E	35.00 BSC		
M/N	33.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	_	_	0.20



1704-Ball Organic fcBGA Package

Dimensions in Millimeters



NOTES:	UNLESS OTHERWISE SPECIFIED	
1.	DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.	
2.	ALL DIMENSIONS ARE IN MILLIMETERS.	
3	DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C	
4	PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.	
5	BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.	
6	EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.	

SYMBOL	MIN.	NOM.	MAX.
A	2.55	2.90	3.25
A1	0.35	0.50	0.65
A2	1.20 REF		
B/C	41.70	42.00	42.30
D/E	42.50 BSC		
M/N	42.50 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
e	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.23